

---

---

**Visokofrekvenčne induktivne komponente – Neelektrične karakteristike in  
merilne metode – 2. del: Preskusne metode za neelektrične karakteristike (IEC  
62025-2:2005)**

High frequency inductive components – Non-electrical characteristics and  
measuring methods – Part 2: Test methods for non-electrical characteristics (IEC  
62025-2:2005)

**iTeh STANDARD PREVIEW**  
**(standards.iteh.ai)**

[SIST EN 62025-2:2005](https://standards.iteh.ai/catalog/standards/sist/edba5f6d-30db-4026-a60f-81d9f73d8807/sist-en-62025-2-2005)

[https://standards.iteh.ai/catalog/standards/sist/edba5f6d-30db-4026-a60f-  
81d9f73d8807/sist-en-62025-2-2005](https://standards.iteh.ai/catalog/standards/sist/edba5f6d-30db-4026-a60f-81d9f73d8807/sist-en-62025-2-2005)

# **iTeh STANDARD PREVIEW** **(standards.iteh.ai)**

SIST EN 62025-2:2005

<https://standards.iteh.ai/catalog/standards/sist/edba5f6d-30db-4026-a60f-81d9f73d8807/sist-en-62025-2-2005>

**High frequency inductive components –  
Non-electrical characteristics and measuring methods  
Part 2: Test methods for non-electrical characteristics  
(IEC 62025-2:2005)**

Composants inductifs à haute fréquence -  
Caractéristiques non électriques  
et méthodes de mesure  
Partie 2: Méthodes d'essai pour  
caractéristiques non électriques  
(CEI 62025-2:2005)

Induktive Hochfrequenzbauelemente -  
Nichtelektrische Eigenschaften  
und Messmethoden  
Teil 2: Messverfahren für nichtelektrische  
Eigenschaften  
(IEC 62025-2:2005)

**iTeh STANDARD PREVIEW**  
**(standards.iteh.ai)**

SIST EN 62025-2:2005

<https://standards.iteh.ai/catalog/standards/sist/edba5f6d-30db-4026-a60f-81d9f73d8807/sist-en-62025-2-2005>

This European Standard was approved by CENELEC on 2005-02-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Cyprus, Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, Netherlands, Norway, Poland, Portugal, Slovakia, Slovenia, Spain, Sweden, Switzerland and United Kingdom.

## CENELEC

European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

**Central Secretariat: rue de Stassart 35, B - 1050 Brussels**

## Foreword

The text of document 51/797/FDIS, future edition 1 of IEC 62025-2, prepared by IEC TC 51, Magnetic components and ferrite materials, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 62025-2 on 2005-02-01.

The following dates were fixed:

- |  |       |            |
|--|-------|------------|
| – latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement | (dop) | 2005-11-01 |
| – latest date by which the national standards conflicting with the EN have to be withdrawn   | (dow) | 2008-02-01 |

Annex ZA has been added by CENELEC.

---

## Endorsement notice

The text of the International Standard IEC 62025-2:2005 was approved by CENELEC as a European Standard without any modification.

**(standards.iteh.ai)**

SIST EN 62025-2:2005

<https://standards.iteh.ai/catalog/standards/sist/edba5f6d-30db-4026-a60f-81d9f73d8807/sist-en-62025-2-2005>

## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE Where an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-1	1988	Environmental testing Part 1: General and guidance	EN 60068-1 <sup>1)</sup>	1994
IEC 60068-2-6 + corr. March	1995 1995	Part 2: Tests - Test Fc: Vibration (sinusoidal)	EN 60068-2-6	1995
IEC 60068-2-20	1979	Part 2: Tests - Test T: Soldering	HD 323.2.20 S3 <sup>2)</sup>	1988
IEC 60068-2-21	1999	Part 2-21: Tests - Test U: Robustness of terminations and integral mounting devices	EN 60068-2-21	1999
IEC 60068-2-27	1987	Part 2: Tests - Test Ea and guidance: Shock	EN 60068-2-27	1993
IEC 60068-2-45	1980	Part 2: Tests - Test Xa and guidance: Immersion in cleaning solvents	EN 60068-2-45	1992
IEC 60068-2-58	2004	Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)	EN 60068-2-58 + corr. December	2004 2004
IEC 60068-2-69	- <sup>3)</sup>	Part 2: Tests - Test Te: Solderability testing of electronic components for surface mount technology by the wetting balance method	EN 60068-2-69	1996 <sup>4)</sup>
IEC 60068-2-77	1999	Part 2-77: Tests - Test 77: Body strength and impact shock	EN 60068-2-77	1999
IEC 61188-5-2	2003	Printed boards and printed board assemblies - Design and use Part 5-2: Attachment (land/joint) considerations - Discrete components	EN 61188-5-2	2003

<sup>1)</sup> EN 60068-1 includes corrigendum October 1988 + A1:1992 to IEC 60068-1.

<sup>2)</sup> HD 323.2.20 S3 includes A2:1987 to IEC 60068-2-20.

<sup>3)</sup> Undated reference.

<sup>4)</sup> Valid edition at date of issue.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61190-1-2	2002	Attachment materials for electronic assembly Part 1-2: Requirements for solder pastes for high-quality interconnections in electronics assembly	EN 61190-1-2	2002
IEC 61190-1-3	2002	Attachment materials for electronic assembly Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solders for electronic soldering applications	EN 61190-1-3	2002
IEC 62211	2003	Inductive components - Reliability management	EN 62211	2004

## iTeh STANDARD PREVIEW (standards.iteh.ai)

SIST EN 62025-2:2005

<https://standards.iteh.ai/catalog/standards/sist/edba5f6d-30db-4026-a60f-81d9f73d8807/sist-en-62025-2-2005>

**NORME  
INTERNATIONALE  
INTERNATIONAL  
STANDARD**

**CEI  
IEC**

**62025-2**

Première édition  
First edition  
2005-01

---

---

**Composants inductifs à haute fréquence –  
Caractéristiques non électriques  
et méthodes de mesure –**

**Partie 2:**

**Méthodes d'essai pour caractéristiques  
non électriques**

**High frequency inductive components –  
Non-electrical characteristics and  
measuring methods –**

**Part 2:**

**Test methods for non-electrical characteristics**

© IEC 2005 Droits de reproduction réservés — Copyright - all rights reserved

Aucune partie de cette publication ne peut être reproduite ni utilisée sous quelque forme que ce soit et par aucun procédé, électronique ou mécanique, y compris la photocopie et les microfilms, sans l'accord écrit de l'éditeur.

No part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying and microfilm, without permission in writing from the publisher.

International Electrotechnical Commission, 3, rue de Varembé, PO Box 131, CH-1211 Geneva 20, Switzerland  
Telephone: +41 22 919 02 11 Telefax: +41 22 919 03 00 E-mail: inmail@iec.ch Web: www.iec.ch



Commission Electrotechnique Internationale  
International Electrotechnical Commission  
Международная Электротехническая Комиссия

CODE PRIX  
PRICE CODE

**T**

Pour prix, voir catalogue en vigueur  
For price, see current catalogue

## CONTENTS

FOREWORD.....	5
1 Scope .....	9
2 Normative references .....	9
3 Terms and definitions .....	11
4 Test conditions .....	11
4.1 Standard atmospheric conditions for test.....	11
4.2 Referee conditions.....	11
5 Mechanical characteristics test .....	13
5.1 Body strength test .....	13
5.2 Robustness of termination (electrode) .....	15
5.3 Solderability .....	27
5.4 Resistance to soldering heat.....	33
5.5 Resistance to dissolution of metallization .....	37
5.6 Vibration.....	39
5.7 Resistance to shock.....	41
Annex A (normative) Mounting of surface mounting inductor to test printed-circuit board ....	45
Figure 1 – Method for pressurizing body.....	13
Figure 2 – Pressurizing jig .....	15
Figure 3 – Example of printed-circuit board.....	17
Figure 4 – Layout.....	21
Figure 5 – Pressurizing jig .....	21
Figure 6 – Pressurizing .....	21
Figure 7 – Pressurizing and shape of jig.....	25
Figure 8 – Reflow temperature profile.....	31
Table 1 – Size of soldering lands by the code of multi-layer chip inductors .....	17
Table 2 – Thickness of solder paste by the size code of inductors.....	19
Table 3 – Conditions of immersion into solder .....	29
Table 4 – Reflow temperature .....	29
Table 5 – Severity.....	33
Table 6 – Reflow temperature .....	35
Table 7 – Conditions of vibration .....	41



## INTERNATIONAL ELECTROTECHNICAL COMMISSION

## HIGH FREQUENCY INDUCTIVE COMPONENTS – NON-ELECTRICAL CHARACTERISTICS AND MEASURING METHODS –

### Part 2: Test methods for non-electrical characteristics

#### FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
- 3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
- 5) IEC provides no marking procedure to indicate its approval and cannot be rendered responsible for any equipment declared to be in conformity with an IEC Publication.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
- 8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
- 9) Attention is drawn to the possibility that some of the elements of this IEC Publication may be the subject of patent rights. IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 62025-2 has been prepared by IEC technical committee 51: Magnetic components and ferrite materials.

The text of this standard is based on the following documents:

FDIS	Report on voting
51/797/FDIS	51/808/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

IEC 62025 consists of the following parts, under the general title *High frequency inductive components – Non-electrical characteristics and measuring methods*

Part 1: Fixed, surface mounted inductors for use in electronic and telecommunication equipment

Part 2: Test methods for non-electrical characteristics

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

## iTeh STANDARD PREVIEW (standards.iteh.ai)

SIST EN 62025-2:2005

<https://standards.iteh.ai/catalog/standards/sist/edba5f6d-30db-4026-a60f-81d9f73d8807/sist-en-62025-2-2005>

# HIGH FREQUENCY INDUCTIVE COMPONENTS – NON-ELECTRICAL CHARACTERISTICS AND MEASURING METHODS –

## Part 2: Test methods for non-electrical characteristics

### 1 Scope

This part of IEC 62025 specifies a test method for the non-electrical characteristics of the Surface Mounted Device (SMD) inductors to be used for electronic and telecommunication equipment. The object of this part of IEC 62025 is to define methods for measuring mechanical performance only. As the reliability performances and specifications relative to non-electrical performances are defined in IEC 62211, detailed measuring methods for mechanical performance of reliability testing are defined in this part of IEC 62025.

### 2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068-1:1988, *Environmental testing – Part 1: General and guidance*

IEC 60068-2-6:1995, *Environmental testing – Part 2: Tests – Test Fc : Vibration (sinusoidal)*

<https://standards.iteh.ai/catalog/standards/sist/edba5f6d-30db-4026-a60f-8149f7348807/sist-ec-62253-2005>

IEC 60068-2-20:1979, *Environmental testing – Part 2: Tests – Test T: Soldering*

IEC 60068-2-21:1999, *Environmental testing – Part 2-21: Tests – Test U: Robustness of terminations and integral mounting devices*

IEC 60068-2-27:1987, *Environmental testing – Part 2: Tests – Test Ea and guidance: Shock*

IEC 60068-2-45:1980, *Environmental testing – Part 2: Tests – Test XA and guidance: Immersion in cleaning solvents*

IEC 60068-2-58:2004, *Environmental testing – Part 2-58: Tests – Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)*

IEC 60068-2-69, *Environmental testing – Part 2: Tests – Test Te: Solderability testing of electronic components for surface mount technology by the wetting balance method*

IEC 60068-2-77:1999, *Environmental testing – Part 2-77: Tests – Test 77: Body strength and impact shock*

IEC 61188-5-2:2003, *Printed boards and printed board assemblies – Design and use – Part 5-2: Attachment (land/joint) considerations – Discrete components*

IEC 61190-1-2:2002, *Attachment materials for electronic assembly – Part 1-2: Requirements for solder pastes for high-quality interconnections in electronics assembly*

IEC 61190-1-3:2002, *Attachment materials for electronic assembly – Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solders for electronic soldering applications*

IEC 62211:2003, *Inductive components – Reliability management*

### 3 Terms and definitions

For the purpose of this part of IEC 62025, the terms and definitions given in the normative references apply.

### 4 Test conditions

#### 4.1 Standard atmospheric conditions for test

Unless otherwise specified in the detail specification, the tests and measurements shall be carried out under standard atmospheric conditions for test as given in 5.3.1 of IEC 60068-1:

- temperature: 15 °C to 35 °C;
- relative humidity: 25 % to 75 %;
- air pressure: 86 kPa to 106 kPa.

In the event of dispute or where required, the measurements shall be repeated using the referee temperatures (as given in 4.2) and such other conditions as are prescribed in this standard.

In addition, when it is difficult to make measurements in standard atmospheric conditions, unless a doubt arises about the validity of the result, the tests and measurements may be performed in non-standard atmospheric conditions.

#### 4.2 Referee conditions

For referee purposes, one of the standard atmospheric conditions for referee tests taken from 5.2 of IEC 60068-1, shall be selected and shall be as follows:

- temperature: 20 °C ± 2 °C;
- relative humidity: 60 % to 70 %;
- air pressure: 86 kPa to 106 kPa.